

ABSTRACT

A high-speed production method of a printed circuit board comprising the steps of, melting and jet-spraying a solid ink on an insulating substrate to be patterned, leaving portions corresponding to an image part unsprayed, coating a side of the insulating substrate patterned with a conductive layer, and removing solid ink portions by solving, wherein the solid ink comprises a wax as a main component, and wherein the melted solid ink is jet-sprayed for patterning in accordance with data from a computer.